Materials Declaration

Package	SOIC
Body Size	150 mils
LeadCount	8
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.2	3.83 E-02	515858
Epoxy resin	7.5	3.33 E-03	44883
Phenol Novolac	4	1.78 E-03	23938
Sb2O3	1.5	6.66 E-04	8977
Brominated Resin	0.5	2.22 E-04	2992
Carbon Black	0.3	1.33 E-04	1795
Subtotal		4.44 E-02	598443

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cd	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Hg	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cr+6	Not Detected	Draft IEC62321. EPA Method 3060A. UV-VIS.
PBB	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.
PBDE	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.34 E-02	315979
Fe	2.35	5.47 E-04	7380
Zn	0.12	3.08 E-05	415
P	0.03	5.82 E-06	79
Subtotal		2.40 E-02	323853

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cd	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Hg	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cr+6	Not Detected	Draft IEC62321. EPA Method 3060A. UV-VIS.
PBB	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.
PBDE	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.43 E-04	3271

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.46 E-03	19685

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.00 E-04	4045

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.63 E-03	35464

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	9.04 E-04	12190
Resin	15	1.70 E-04	2286
Curing agent & hardener	5	5.65 E-05	762
Subtotal		1.13 E-03	15238

Package Totals

Weight (g)	PPM
7.42 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	SOIC
Body Size	150 mils
LeadCount	8
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.2	3.83 E-02	515858
Epoxy resin	7.5	3.33 E-03	44883
Phenol Novolac	4	1.78 E-03	23938
Sb2O3	1.5	6.66 E-04	8977
Brominated Resin	0.5	2.22 E-04	2992
Carbon Black	0.3	1.33 E-04	1795
Subtotal		4.44 E-02	598443

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cd	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Hg	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cr+6	Not Detected	Draft IEC62321. EPA Method 3060A. UV-VIS.
PBB	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.
PBDE	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.34 E-02	315979
Fe	2.35	5.47 E-04	7380
Zn	0.12	3.08 E-05	415
P	0.03	5.82 E-06	79
Subtotal		2.40 E-02	323853

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cd	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Hg	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cr+6	Not Detected	Draft IEC62321. EPA Method 3060A. UV-VIS.
PBB	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.
PBDE	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.43 E-04	3271

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.24 E-03	16733
Pb	15	2.19 E-04	2953
Subtotal		1.46 E-03	19685

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.00 E-04	4045

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.63 E-03	35464

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	9.04 E-04	12190
Resin	15	1.70 E-04	2286
Curing agent & hardener	5	5.65 E-05	762
Subtotal		1.13 E-03	15238

Package Totals

Weight (g)	PPM
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